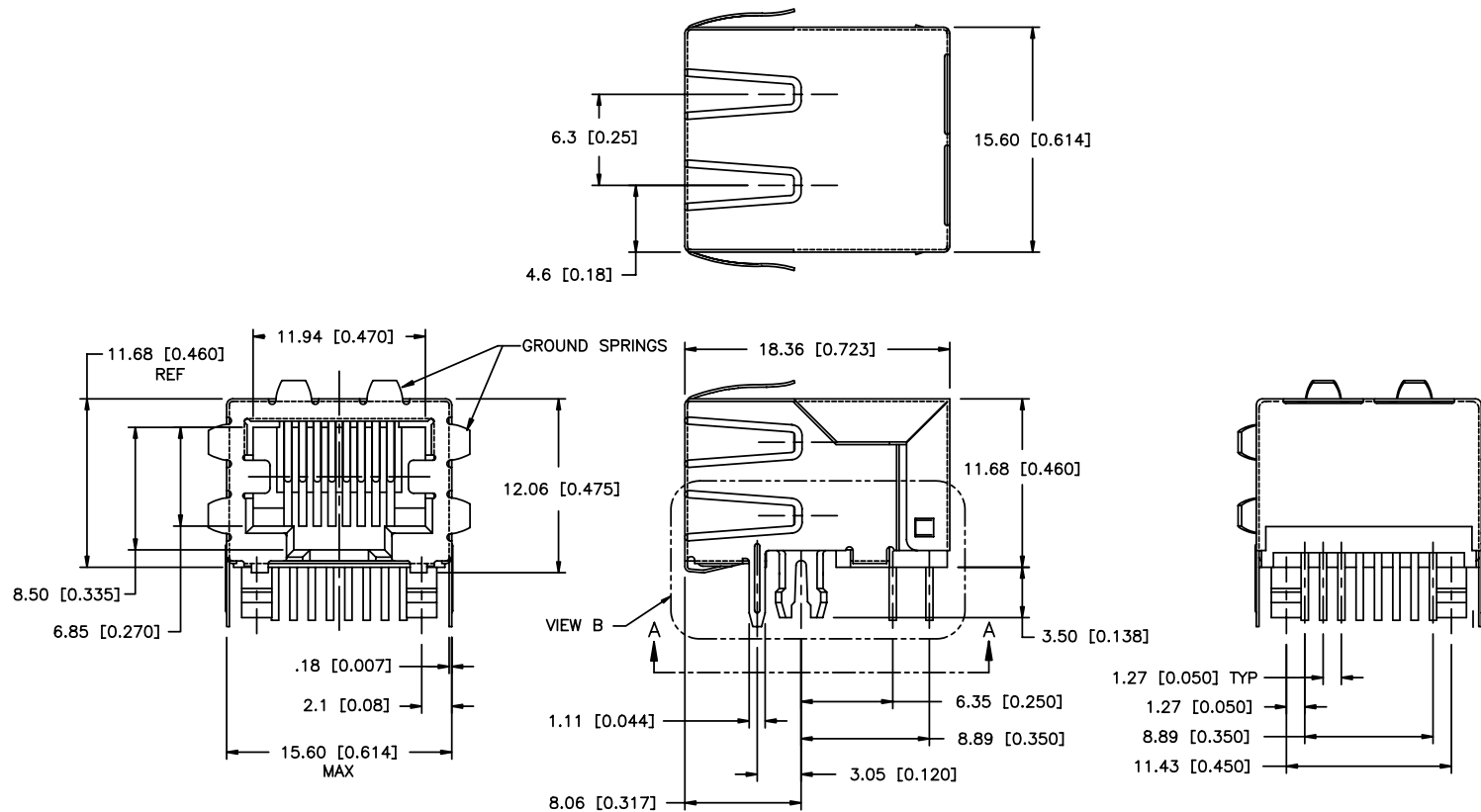
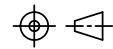




PRODUCT NO.
SEE TABLE



mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY	 www.fciconnect.com		
ltr	ecn no	dr	date						
F	V80459	LP	3/25/98	linear	.XX±.13/.XXX ±.005	projection	title 8 POS LOW PROFILE PCB III SHIELDED MODJACK ASSEMBLY		
G	V81277	GAH	3/25/98		.XXX±.051/.XXXX ±.0020				
H	V81819	CGC	10/27/98	angles	0° ±2°	MM/INCH	product family MODJACK code size dwg no 213		
J	V00470	BKB	2/1/00	dr	G.HULL 5/28/96	scale			
K	V01040	CSP	6/1/00	enr	Y.BELOPOLSKY 5/28/96	2:1	A 72231		
L	V03-1103	PJ	10/16/03	chr	R.HOLLER 5/28/96				
M	M05-0066	ERE	04/15/05	appd	Y.BELOPOLSKY 5/28/96		sheet 1 of 3		
sheet	revision	M	L	M					
index	sheet	1	2	3					

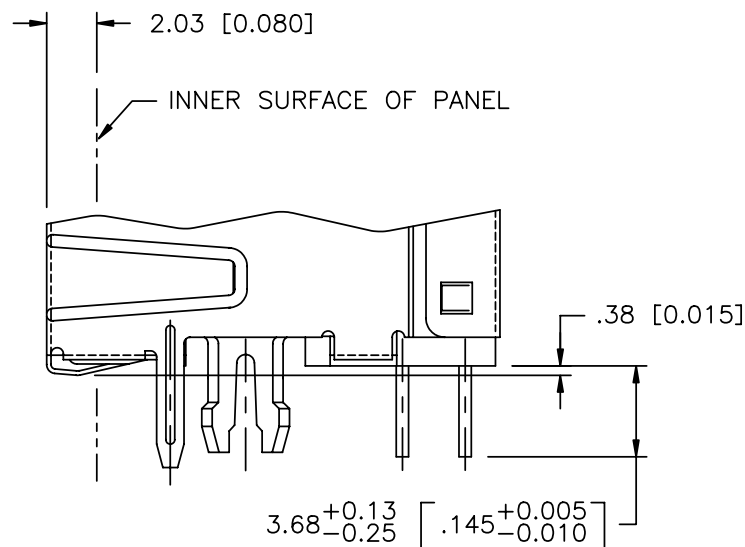
cage code



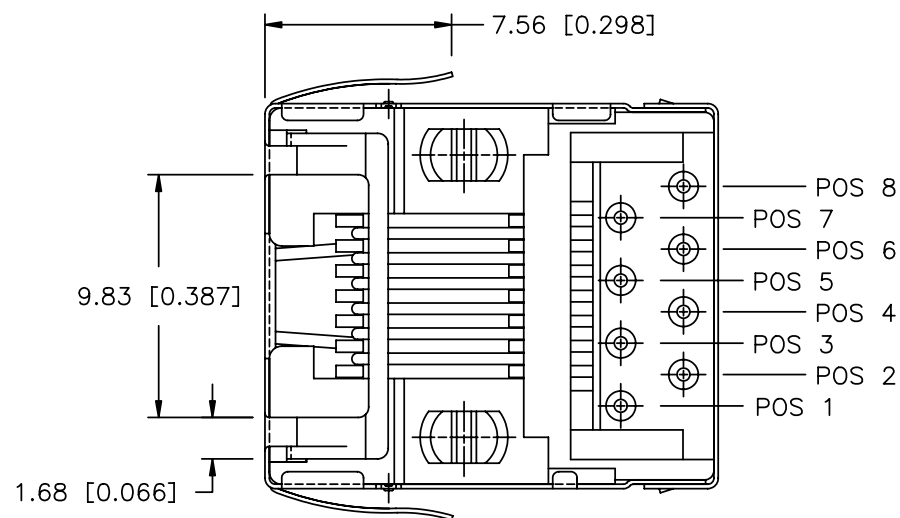
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PRODUCT NO.
SEE TABLE



VIEW B



VIEW A-A

mat'l. code				tolerances unless otherwise specified			CUSTOMER COPY		 www.fciconnect.com			
ltr	ecn no	dr	date	linear	.X±.3/.XX ±.01/			projection 	title 8 POS LOW PROFILE PCB III SHIELDED MODJACK ASSEMBLY			
L					.XX±.13/.XXX ±.005							
					.XXX±.051/.XXXX ±.0020							
				angles	0° ±2°			 MM/INCH	product family		MODJACK	code
				dr	G.HULL	5/28/96	scale 2:1		size dwg no		213	
				enrg	Y.BELOPOLSKY	5/28/96			A 72231		sheet 2 of 3	
				chr	R.HOLLER	5/28/96						
				appd	Y.BELOPOLSKY	5/28/96						
sheet index	revision sheet											

cage code

ACAD

PDM: Rev:M

STATUS: Released 26 Printed: Feb 20, 2010



PRODUCT NO. SEE TABLE		CODE Z		GROUND SPRING CONFIGURATIONS		DIAGRAM #1		DIAGRAM #2		DIAGRAM #3		DIAGRAM #4	
		1		DIAGRAM #1									
		2		DIAGRAM #2									
		3		DIAGRAM #3									
		4		DIAGRAM #4									

GROUND SPRING CONFIGURATIONS AS VIEWED FROM PORT SIDE

NOTE: PLEASE CHECK FOR AVAILABILITY, NOT ALL OPTIONS AVAILABLE.

PRODUCT NO. 72231-X8YZLF	8 POSITION HOUSING	OPTIONAL LOADING CODE Y	POSITIONS LOADED
		4	3,4,5,6
		6	2,3,4,5,6,7
		8	ALL POS

PLATING CODE X	PLATING ⑨
0	.76uM/30u" GXT
3	.76uM/30u" Au
5	1.27uM/50u" Au OVER Ni

RECOMMENDED P.C.B. LAYOUT
AS VIEWED FROM TOP SIDE (COMPONENT SIDE)

RECOMMENDED PANEL OPENING

NOTES:

1. RECOMMENDED P.C.B. THICKNESS 1.60 [0.063].
2. HOUSING MATL: HIGH TEMPERATURE THERMOPLASTIC MATERIAL, UL94V-0, COLOR BLACK.
3. CONTACTS MATL: PHOS BRONZE ALLOY ROUND WIRE. SEE TABLE FOR PLATING.
4. SHIELD MATL: PHOS BRONZE ALLOY, BRIGHT TIN PLATE OVER NICKEL UNDERPLATING PER BUS-15-002/M.
5. TWO LAYERS OF HIGH TEMP. INSULATING TAPE BETWEEN SHIELD AND SIGNAL CONTACTS.
- ⑥. LF SUFFIX AT THE END OF PART NUMBER IS LEAD FREE.
7. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 15 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.5mm MINIMUM THICK CIRCUIT BOARD. SEE APPLICATION NOTES/PROCEDURES IF THEY ARE AVAILABLE.
- ⑧. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN GS-22-008.
- ⑨. PLATING OPTIONS:
MAY BE EITHER GOLD OR GXT PLATED AT MANUFACTURER'S OPTION.

mat'l. code				tolerances unless otherwise specified				CUSTOMER COPY		FCI www.fciconnect.com	
ltr	ecr no	dr	date	linear	.X±.3/.XX ±.01			projection 	title 8 POS LOW PROFILE PCB III SHIELDED MODJACK ASSEMBLY	product family MODJACK	code 213
M					.XX±.13/.XXX ±.005						
					.XXX±.051/.XXX ±.0020						
				angles	0° ±2°			MM/INCH scale 2:1	size 72231	sheet 3 of 3	
				dr	G.HULL 5/28/96						
				enr	Y.BELOPOLSKY 5/28/96						
				chr	R.HOLLER 5/28/96			A			
				appd	Y.BELOPOLSKY 5/28/96						
sheet index	revision sheet										